

**Semiconductor Package Including Leadframe Roughened
Using Chemical Etchant To Prevent Separation
Between Leadframe And Molding Compound**

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Abstract

10 A semiconductor package contains a metal leadframe that has been specially
adhesion between the leadframe and the molten plastic during the encapsulation of the
leadframe and thereby reduces the tendency of the package to separate when exposed to
moisture and numerous temperature cycles. In one embodiment, the leadframe made of
15 copper is roughened with a chemical etchant that contains sulfuric acid and hydrogen
peroxide.